

Title (en)

COMPOSITE MOLDING AND PRODUCTION METHOD THEREFOR

Title (de)

VERBUNDSTOFFFORMVERFAHREN UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

MOULAGE COMPOSITE ET PROCÉDÉ DE PRODUCTION POUR CELUI-CI

Publication

EP 3835058 A4 20211006 (EN)

Application

EP 19846851 A 20190808

Priority

- JP 2018151386 A 20180810
- JP 2019031354 W 20190808

Abstract (en)

[origin: EP3835058A1] The present invention provides a composite molded body in which a rubber layer in the form of a thin film is formed on a surface of a resin molded body and a production method therefor. According to an embodiment of the present invention, a liquid composition containing a rubber component such as a rubber latex and a peroxide is applied to a surface of a resin molded body such as a polyamide-based resin having an amino group, causing crosslinking to occur in an uncrosslinked rubber layer and forming a crosslinked rubber layer in the form of a thin film. When a co-crosslinking agent is used in combination, adhesion to the resin molded body can be improved even when the thickness of the crosslinked rubber layer is small.

IPC 8 full level

C08J 7/043 (2020.01); **B05D 1/42** (2006.01); **B05D 3/02** (2006.01); **B05D 7/02** (2006.01)

CPC (source: EP US)

B05D 7/02 (2013.01 - US); **B05D 7/24** (2013.01 - US); **C08J 7/0427** (2020.01 - EP US); **C08J 7/043** (2020.01 - EP); **B05D 1/42** (2013.01 - EP); **B05D 3/0254** (2013.01 - EP); **B05D 7/02** (2013.01 - EP); **C08J 2377/00** (2013.01 - EP); **C08J 2377/06** (2013.01 - EP US); **C08J 2421/02** (2013.01 - EP)

Citation (search report)

[X] US 5132182 A 19920721 - GROSSE-PUPPENDAHL THOMAS [DE], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 3835058 A1 20210616; **EP 3835058 A4 20211006**; CN 112512797 A 20210316; JP 2020026067 A 20200220; JP 7181727 B2 20221201; TW 202017985 A 20200516; TW 202424068 A 20240616; US 11673162 B2 20230613; US 2021308719 A1 20211007; WO 2020032170 A1 20200213

DOCDB simple family (application)

EP 19846851 A 20190808; CN 201980050211 A 20190808; JP 2018151386 A 20180810; JP 2019031354 W 20190808; TW 108128391 A 20190808; TW 113107766 A 20190808; US 201917263081 A 20190808